

Title (en)  
ELECTROCHEMICAL DEPOSITION SYSTEM FOR A CHEMICAL AND/OR ELECTROLYTIC SURFACE TREATMENT OF A SUBSTRATE

Title (de)  
ELEKTROCHEMISCHES ABSCHIEDUNGSSYSTEM FÜR EINE CHEMISCHE UND/ODER ELEKTROLYTISCHE OBERFLÄCHENBEHANDLUNG EINES SUBSTRATS

Title (fr)  
SYSTÈME DE DÉPÔT ÉLECTROCHIMIQUE POUR UN TRAITEMENT DE SURFACE CHIMIQUE ET/OU ÉLECTROLYTIQUE D'UN SUBSTRAT

Publication  
**EP 3868923 A1 20210825 (EN)**

Application  
**EP 20158350 A 20200219**

Priority  
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Abstract (en)  
The invention relates to an electrochemical deposition system for a chemical and/or electrolytic surface treatment of a substrate, a module for chemical and/or electrolytic surface treatment of a substrate in a process fluid, a use of the electrochemical deposition system or the module for chemical and/or electrolytic surface treatment for a metal deposition application and a manufacturing method for an electrochemical deposition system for a chemical and/or electrolytic surface treatment of a substrate. The electrochemical deposition system comprises an anode, an anode enclosure, and a single electrolyte. The anode enclosure extends at least partially around the anode. The anode enclosure comprises a membrane. The anode and the anode enclosure are arranged in the single electrolyte. The single electrolyte is the only electrolyte of the electrochemical deposition system.

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Citation (applicant)  
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